



Press Release

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X-ES Introduces Rugged COM Express® Module for Small Form Factor Systems

Middleton, WI – March 14, 2012 – Extreme Engineering Solutions, Inc. (X-ES) has introduced the company's first ruggedized COM Express® module, the [XPedite5550](#), which complies with the PICMG COM Express Compact form factor (95mm x 95mm) and supports an enhanced Type-5 pinout. The [XPedite5550](#) can be hosted on a standard COM Express carrier card, hosted on a custom carrier card built to include any additional requirements from the end user, or integrated into the X-ES [XPand6000 Series of Small Form Factor \(SFF\)](#) rugged systems.

Designed and tested for the harshest military, aerospace, and industrial environments, the [XPedite5550](#) includes enhancements above and beyond commercial COM Express modules to provide a rugged and reliable COTS processor mezzanine solution:

- Incorporates the same design and manufacturing principles as all X-ES Level-5 rugged products
- Designed and tested for full operation from -40 to +85°C
- Additional mounting holes for increased structural integrity
- Extended shock and vibration capabilities for full operation in the harshest environments
- Conduction-cooled and air-cooled applications supported by single design
- Soldered down memory replaces less rugged and less reliable SO-DIMMs
- Tin-lead manufacturing process to mitigate tin-whisker effects (RoHS-compliant process is also available)
- BIT support

Targeting Freescale QorIQ™ P1011, P1020, P2010, and P2020 processors with clock speeds of up to 1.2 GHz, the [XPedite5550](#) features up to 8 GB of DDR3-800, x2 and x1 PCI Express interfaces, three Gigabit Ethernet ports, two SATA 3.0 Gb/s ports, two serial ports, and a USB 2.0 port. BSPs for Linux, INTEGRITY, and VxWorks are available. QNX, LynxOS, and other O/S support may be available as needed.

The [XPedite5550](#) was developed with the rugged [XPand6000 SFF systems](#) in mind. Supporting conduction cooling, natural convection cooling, and minimal SWaP, an XPand6000-based system can be bolted to almost any available surface of a small UAV or ground vehicle. Weighing as little as 3.5 lbs., [XPand6000 systems](#) provide both high-performance processing capabilities and a multitude of I/O functions added via PMCs/XMCs, including MIL-STD-1553, serial, router, and storage capability in an extremely small and lightweight package.

About X-ES — Extreme Engineering Solutions, Inc. (X-ES) designs and builds chassis, single-board computers, I/O, power, backplane, and system-level products within the embedded computer industry. X-ES offers cutting-edge performance and flexibility in design, plus an unparalleled level of customer support and service. For further information on X-ES products or services, please visit our website: www.xes-inc.com or call (608) 833-1155.

Data Sheet: <http://www.xes-inc.com/assets/products/files/XPedite5550-DS.pdf>

Press Photo: http://www.xes-inc.com/assets/photos/content/112527_XPedite5550.jpg

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